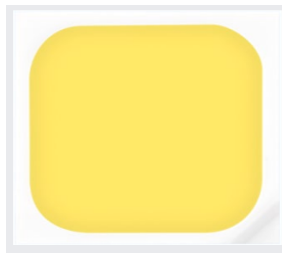


SPECIFICATIONS

Middle Power LED Series
3030
LM301D
CRI 90



Features & Benefits

- 0.3W Class middle power LED
- Mold resin for high reliability
- Standard form factor for design flexibility (3.0 × 3.0 mm)

Dongbu LED Co., Ltd.

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1. Product Code Information

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S	P	M	W	H	3	3	2	6	M	S	7	W	A	V	0	S	D

Digit	PKG Information	Code	Specification			
1 2 3	Dongbu Package Middle Power	SPM	Mddle power			
4 5	Color	WH	White			
6	Product Version	3	Zener-in			
7 8 9	Form Factor	32A	3.0 x 3.0 x 0.65 mm 2 pads			
10	Sorting Current (mA)	M	65 mA			
11	Chromaticity Coordinates	S	MacAdam			
12	CRI	7	Min. 90			
13 14	Forward Voltage (V)	WA	2.57~2.87	Bin Code	AY	2.57~2.67
					AZ	2.67~2.77
					A1	2.77~2.87
		WZ	2.67~2.77	AZ	2.67~2.77	
“WA or WZ” (4,000ea per reel) , “KA or KZ” (16,000ea per reel)						
15 16	CCT (K)	W☆	2700	Bin Code	WN, WP, WA, WR, WS, WT, WU	
		V☆	3000		VN, VP, VQ, VR, VS, VT, VU	
		U☆	3500		UN, UP, UQ, UR, US, UT, UU	
		T☆	4000		TN, TP, TQ, TR, TS, TT, TU	
		R☆	5000		RN, RP, RQ, RR, RS, RT, RU	
		Q☆	5700		QN, QP, QQ, QR, QS, QT, QU	
		P☆	6500		PN, PP, PQ, PR, PS, PT, PU	
		☆ : "0" (Whole Bin) or "Y"(Y Kitting) or "3"(MacAdam 3 step)				
17 18	Luminous Flux (lm)	SD	Bin Code	SD		

2. Characteristics

(1) Absolute Maximum Ratings

Item	Symbol	Rating	Unit	Condition
Ambient / Operating Temperature	T_a	-40 ~ +85	°C	
Storage Temperature	T_{stg}	-40 ~ +100	°C	
LED Junction Temperature	T_j	125	°C	
Forward Current	I_F	400	mA	
Peak Pulsed Forward Current	I_{FP}	600	mA	Duty 1/10, pulse width 10ms
Assembly Process Temperature	-	260<10	°C/S	
ESD (HBM)	-	5	KV	

(2) Electro-optical Characteristics ($I_F = 65 \text{ mA}$, $T_s = 25 \text{ °C}$)

Item	Unit	Rank	Bin	Min.	Typ.	Max.
Forward Voltage (VF)	V	WA	AY	2.57	-	2.67
			AZ	2.67	-	2.77
			A1	2.77		2.87
		WZ	AZ	2.67	-	2.77
Reverse Voltage (@ 5 mA)	V			0.7	-	1.2
Color Rendering Index (Ra)	-	3		90	-	-
R9	-			50		-
Thermal Resistance (junction to solder point)	°C/W			-	12	-
Beam Angle	°			-	120	-

* Note

Dongbu maintains measurement tolerance of: forward voltage = $\pm 0.1 \text{ V}$, luminous flux = $\pm 5 \%$, CRI = ± 3

(4) Luminous Flux Bins ($I_F = 65 \text{ mA}$, $T_s = 25^\circ\text{C}$)

Nominal CCT (K)	CRI Min.	Product Code	Flux Bin	Flux Range (Φ_v , lm)
2700	90	SPMWH3326MS7W★W☆SD	SD	26.5 ~ 29.0
3000	90	SPMWH3326MS7W★V☆SD	SD	27.5 ~ 30.0
3500	90	SPMWH3326MS7W★U☆SD	SD	28.5 ~ 31.0
4000	90	SPMWH3326MS7W★T☆SD	SD	29.5 ~ 32.0
5000	90	SPMWH3326MS7W★R☆SD	SD	30.0 ~ 32.5
5700	90	SPMWH3326MS7W★Q☆SD	SD	29.0 ~ 31.5
6500	90	SPMWH3326MS7W★P☆SD	SD	29.0 ~ 31.5

* Note :

"●" can be "0" (Whole bin), "K" (K Kitting bin), "S"(S Kitting bin) of the color binning

(5) Kitting rule

a) Y Kitting Bin Concept

1. Under agreement between customer and Dongbu LED, Dongbu can supply kitting bin (VF, Color, lm).
2. A Chromaticity Coordinates of kitting bin is mixed by kitting procedure.(below kitting simulation)

[Kitting example]



[Binning Information]

	Bin #1	Bin #2
VF	AY	AY
	AZ	AZ
	A1	A1
CIE	U	U
	N	N
	P	P
	Q	Q
IV	SD	SD

(6) Color Bins ($I_F = 65 \text{ mA}$, $T_s = 25^\circ \text{C}$)

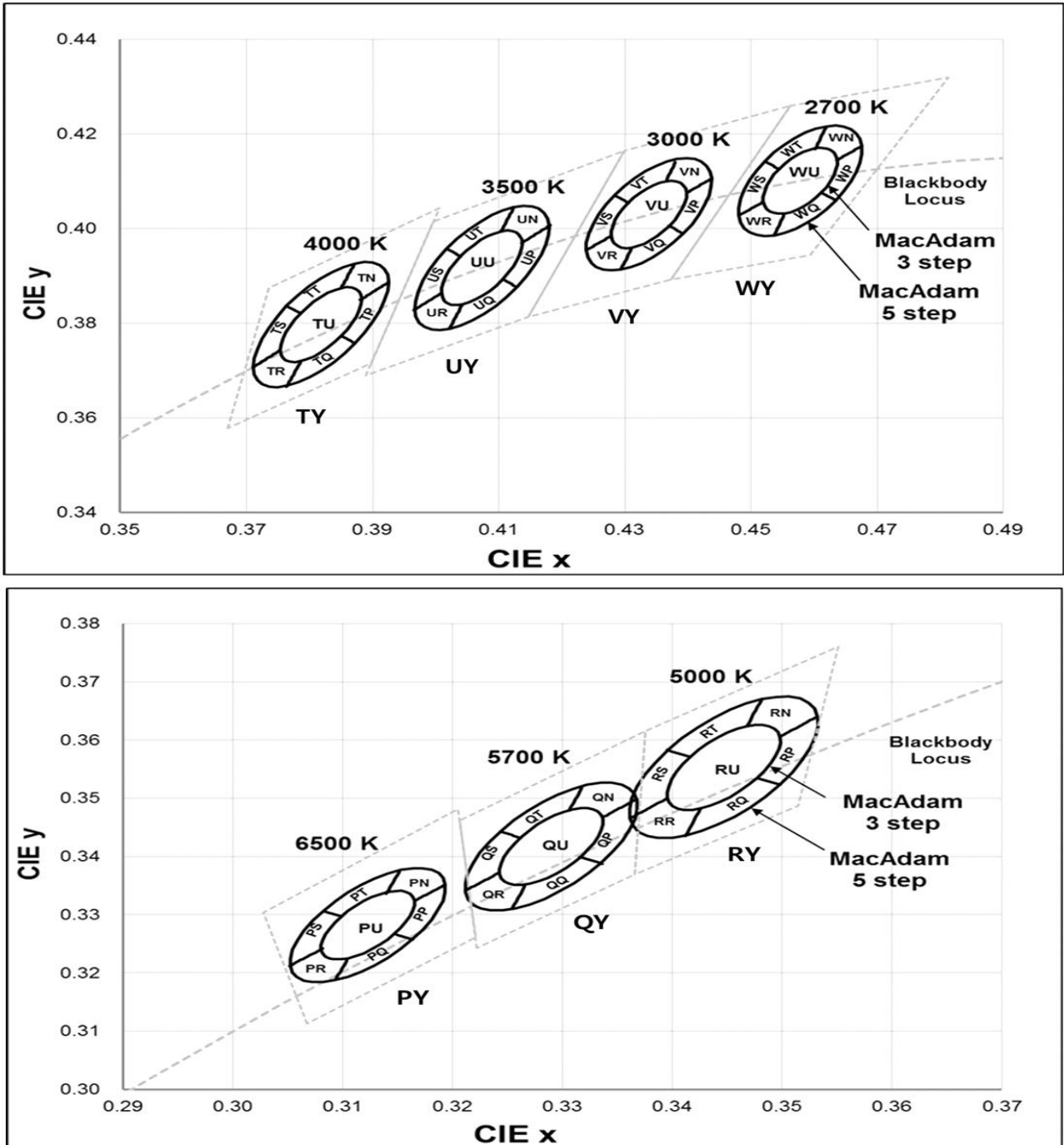
CRI (Ra) Min.	Normal CCT (K)	Product Code	Color Rank	Chromaticity Bins
70	2700	SPMWH3326MS7W ★W0SD	W0 (Whole bin)	WN, WP, WQ, WR, WS, WT, WU
		SPMWH3326MS5W ★W3SD	W3 (MacAdam)	WU
		SPMWH3326MS5W ★WYSD	WY (Y Kitting)	WN, WP, WQ, WR, WS, WT, WU
	3000	SPMWH3326MS7W ★V0SD	V0 (Whole bin)	VN, VP, VQ, VR, VS, VT, VU
		SPMWH3326MS7W ★V3SD	V3 (MacAdam)	VU
		SPMWH3326MS7W ★VYSD	VY (Y Kitting)	VN, VP, VQ, VR, VS, VT, VU
	3500	SPMWH3326MS7W ★U0SD	U0 (Whole bin)	UN, UP, UQ, UR, US, UT, UU
		SPMWH3326MS5W ★U3SD	U3 (MacAdam)	UU
		SPMWH3326MS7W ★UYSD	UY (Y Kitting)	UN, UP, UQ, UR, US, UT, UU
	4000	SPMWH3326MS5W ★T0SD	T0 (Whole bin)	TN, TP, TQ, TR, TS, TT, TU
		SPMWH3326MS7W ★T3SD	T3 (MacAdam)	TU
		SPMWH3326MS5W ★TYSD	TY (Y Kitting)	TN, TP, TQ, TR, TS, TT, TU
	5000	SPMWH3326MS7W ★R0SD	R0 (Whole bin)	RN, RP, RQ, RR, RS, RT, RU
		SPMWH3326MS5W ★R3SD	R3 (MacAdam)	RU
		SPMWH3326MS7W ★RYSD	RY (Y Kitting)	RN, RP, RQ, RR, RS, RT, RU
	5700	SPMWH3326MS7W ★Q0SD	Q0 (Whole bin)	QN, QP, QQ, QR, QS, QT, QU
		SPMWH3326MS7W ★Q3SD	Q3 (MacAdam)	QU
		SPMWH3326MS7W ★QYSD	QY (Y Kitting)	QN, QP, QQ, QR, QS, QT, QU
	6500	SPMWH3326MS7W ★P0SD	P0 (Whole bin)	PN, PP, PQ, PR, PS, PT, PU
		SPMWH3326MS7W ★P3SD	P3 (MacAdam)	PU
		SPMWH3326MS7W ★PYSD	PY (Y Kitting)	PN, PP, PQ, PR, PS, PT, PU

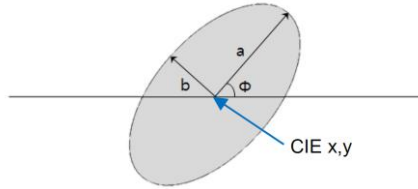
Note: "★" can be "A"(Whole bin), "Z"(AZ Single bin)

(7) Voltage Bins ($I_F = 65 \text{ mA}$, $T_a = 25^\circ \text{C}$)

CRI (Ra) Min.	Nominal CCT (K)	Product Code	Voltage Rank	Voltage Bin	Voltage Range (V)
-	-	-	WA	AY	2.57 ~ 2.67
				AZ	2.67 ~ 2.77
				A1	2.77 ~ 2.87
			WZ	AZ	2.67 ~ 2.77

(8) Chromaticity Region & Coordinates ($I_F = 65 \text{ mA}$, $T_s = 25^\circ\text{C}$)



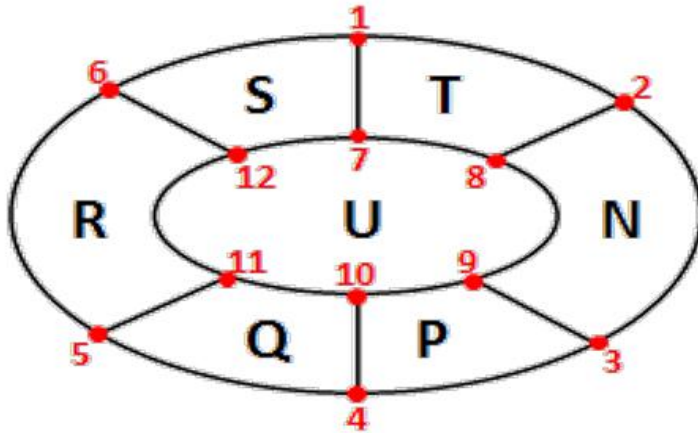
(9) Chromaticity Region & Coordinates ($I_F = 65 \text{ mA}$, $T_s = 25^\circ\text{C}$)


MacAdam	CCT (K)	Center point		Major-axis	Minor-axis	Rotation
		CIE x	CIE y	a	b	Φ
3 step	2700	0.4578	0.4101	0.0081	0.0042	53.70
	3000	0.4338	0.4030	0.0083	0.0041	53.22
	3500	0.4073	0.3917	0.0093	0.0041	54.00
	4000	0.3818	0.3797	0.0094	0.0040	53.72
	5000	0.3447	0.3553	0.0082	0.0035	59.62
	5700	0.3287	0.3417	0.0075	0.0032	59.10
	6500	0.3123	0.3282	0.0067	0.0029	58.57
5 step	2700	0.4578	0.4101	0.0135	0.0070	53.70
	3000	0.4338	0.4030	0.0138	0.0068	53.22
	3500	0.4073	0.3917	0.0155	0.0068	54.00
	4000	0.3818	0.3797	0.0157	0.0067	53.72
	5000	0.3447	0.3553	0.0137	0.0058	59.62
	5700	0.3287	0.3417	0.0125	0.0053	59.10
	6500	0.3123	0.3282	0.0112	0.0048	58.57

* Note :

Dongbu maintains measurement tolerance of: $C_x, C_y = \pm 0.005$

(10) Chromaticity Region & Coordinates



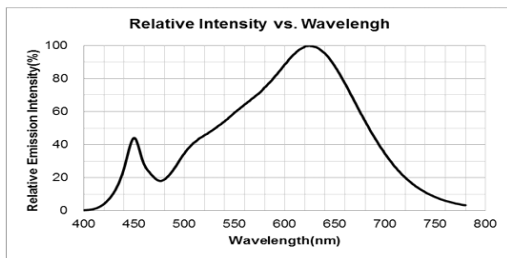
Region	2700K		3000K		3500K		4000K	
	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y
1	0.4521	0.4142	0.4283	0.4071	0.4018	0.4283	0.4071	0.4018
2	0.4619	0.4216	0.4382	0.4146	0.4125	0.4382	0.4146	0.4125
3	0.4675	0.4175	0.4437	0.4105	0.4180	0.4437	0.4105	0.4180
4	0.4634	0.4059	0.4393	0.3989	0.4128	0.4393	0.3989	0.4128
5	0.4537	0.3986	0.4293	0.3913	0.4022	0.4293	0.3913	0.4022
6	0.4481	0.4028	0.4239	0.3954	0.3966	0.4239	0.3954	0.3966
7	0.4544	0.4126	0.4305	0.4054	0.4040	0.4305	0.4054	0.4040
8	0.4603	0.4170	0.4364	0.4100	0.4104	0.4364	0.4100	0.4104
9	0.4636	0.4145	0.4397	0.4075	0.4137	0.4397	0.4075	0.4137
10	0.4612	0.4076	0.4371	0.4005	0.4106	0.4371	0.4005	0.4106
11	0.4553	0.4032	0.4311	0.3960	0.4042	0.4311	0.3960	0.4042
12	0.4520	0.4057	0.4279	0.3984	0.4009	0.4279	0.3984	0.4009

Region	5000K		5700K		6500K	
	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y
1	0.3397	0.3583	0.3242	0.3445	0.3082	0.3307
2	0.3482	0.3670	0.3320	0.3524	0.3153	0.3377
3	0.3532	0.3640	0.3365	0.3496	0.3194	0.3352
4	0.3497	0.3524	0.3333	0.3390	0.3164	0.3257
5	0.3412	0.3436	0.3254	0.3310	0.3093	0.3187
6	0.3362	0.3465	0.3209	0.3338	0.3052	0.3212
7	0.3417	0.3571	0.3260	0.3434	0.3098	0.3297
8	0.3468	0.3623	0.3307	0.3481	0.3141	0.3339
9	0.3498	0.3605	0.3334	0.3464	0.3166	0.3324
10	0.3477	0.3535	0.3314	0.3401	0.3148	0.3267
11	0.3426	0.3483	0.3267	0.3353	0.3105	0.3225
12	0.3396	0.3500	0.3240	0.3369	0.3080	0.3240

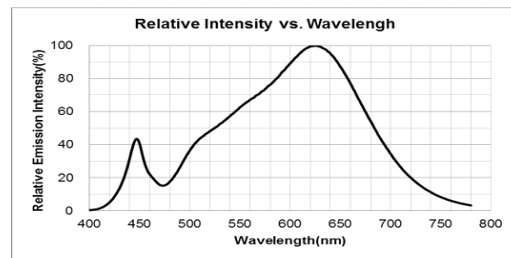
3. Typical Characteristics Graphs

(1) Spectrum Distribution ($I_F = 65 \text{ mA}$, $T_s = 25^\circ\text{C}$)

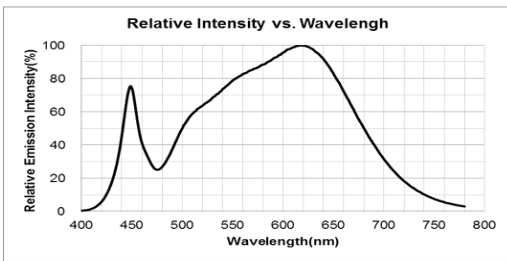
CCT : 2700 K (90 CRI)



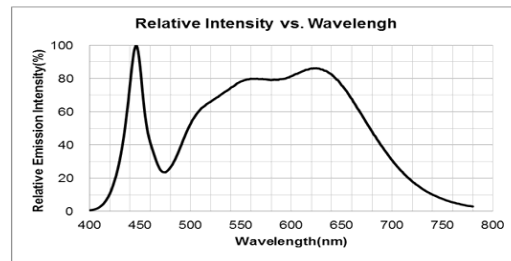
CCT : 3000 K (90 CRI)



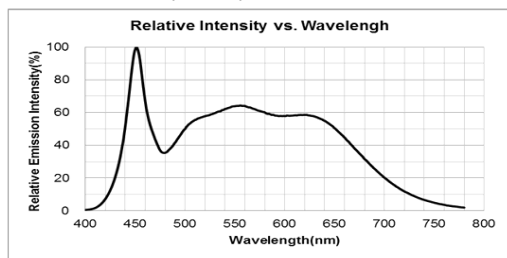
CCT : 3500 K (90 CRI)



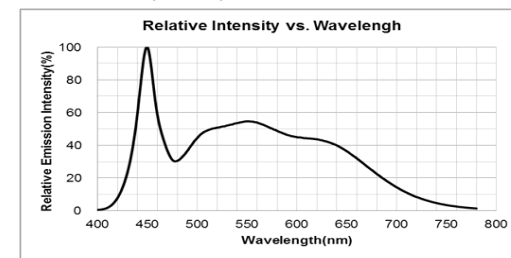
CCT : 4000 K (90 CRI)



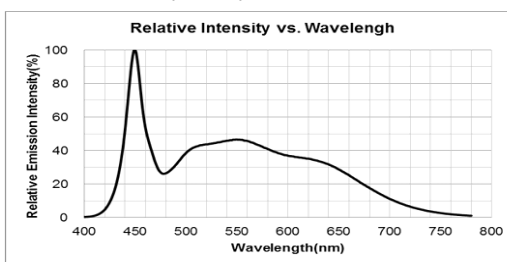
CCT : 5000 K (90 CRI)



CCT : 5900 K (90 CRI)

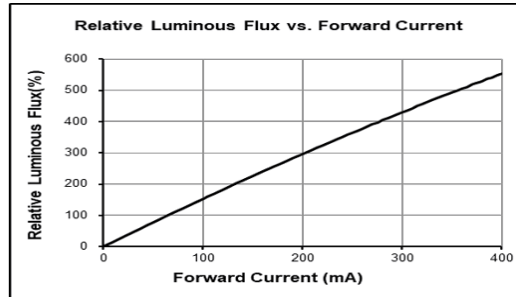
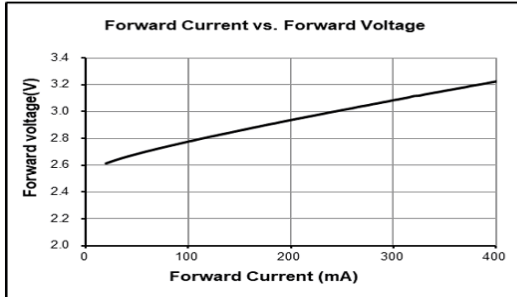


CCT : 6500 K (90 CRI)

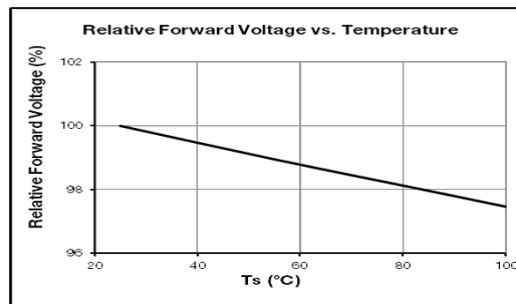
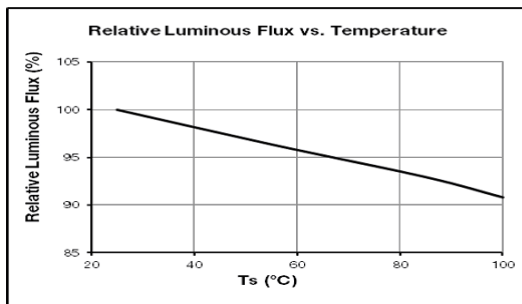


3. Typical Characteristics Graphs

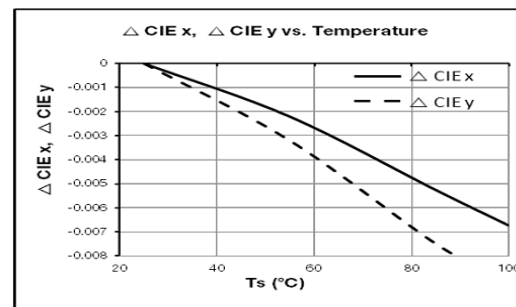
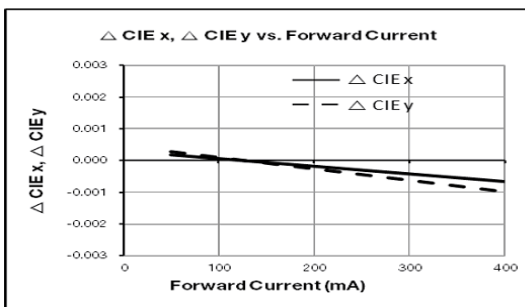
(2) Forward Current Characteristics ($T_s=25\text{ }^{\circ}\text{C}$)



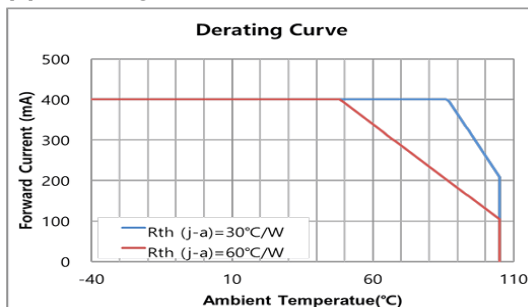
(3) Temperature Characteristics ($I_F=65\text{ mA}$)



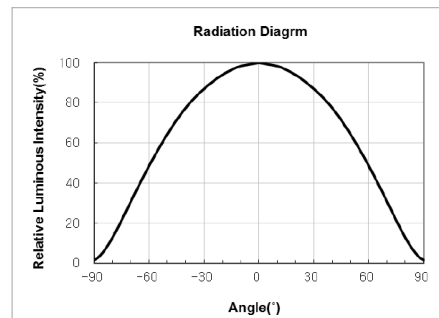
(4) Color Shift Characteristics ($I_F=65\text{ mA}$, $T_a=25\text{ }^{\circ}\text{C}$)



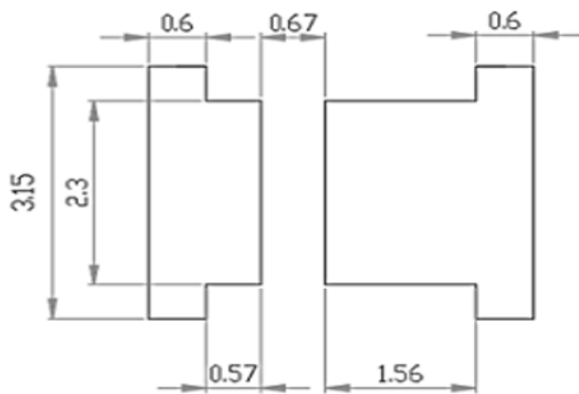
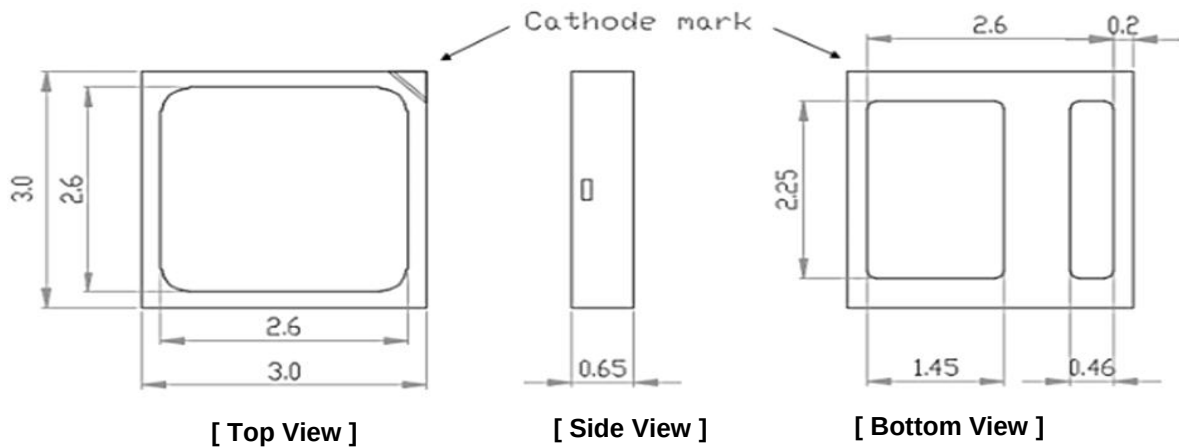
(5) Derating Curve



(6) Beam Angle Characteristics ($I_F=65\text{ mA}$, $T_a=25\text{ }^{\circ}\text{C}$)



4. Outline Drawing & Dimension



[Recommended PCB Solder Pad]

- Measurement unit : mm
- Tolerance : $\pm 0.1\text{mm}$

*** Note :**

- 1) This LED has built-in ESD protection device(s) connected in parallel to LED chip(s).
- 2) T_s point and measurement method:
 - ① Measure one point at the cathode pad, if necessary remove PSR of PCB to reach T_s point.
 - ② All pads must be soldered to the PCB to dissipate heat properly, otherwise the LED can be damaged

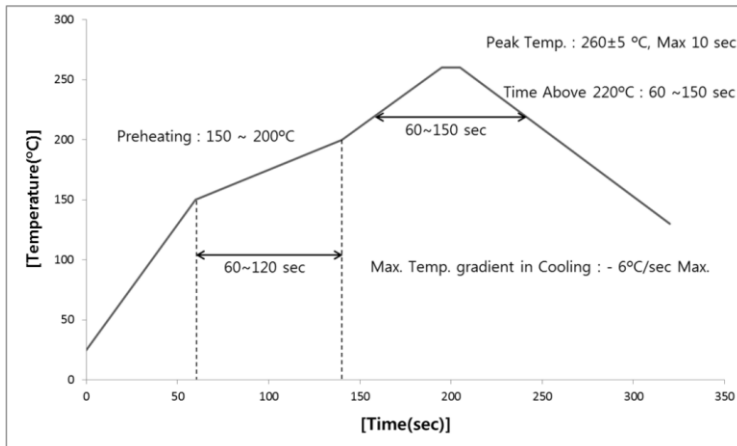
Precautions:

- 1) Pressure on the LEDs will influence to the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the LEDs. Do not put stress on the LEDs during heating.
- 2) Re-soldering should not be done after the LEDs have been soldered. If re-soldering is unavoidable, LED's characteristics should be carefully checked before and after such repair.
- 3) Do not stack assembled PCBs together. Since materials of LEDs is soft, abrasion between two PCB assembled with LED might cause catastrophic failure of the LEDs.

5. Soldering Conditions

(1) Reflow Conditions (Pb free)

Reflow frequency: 2 times max.



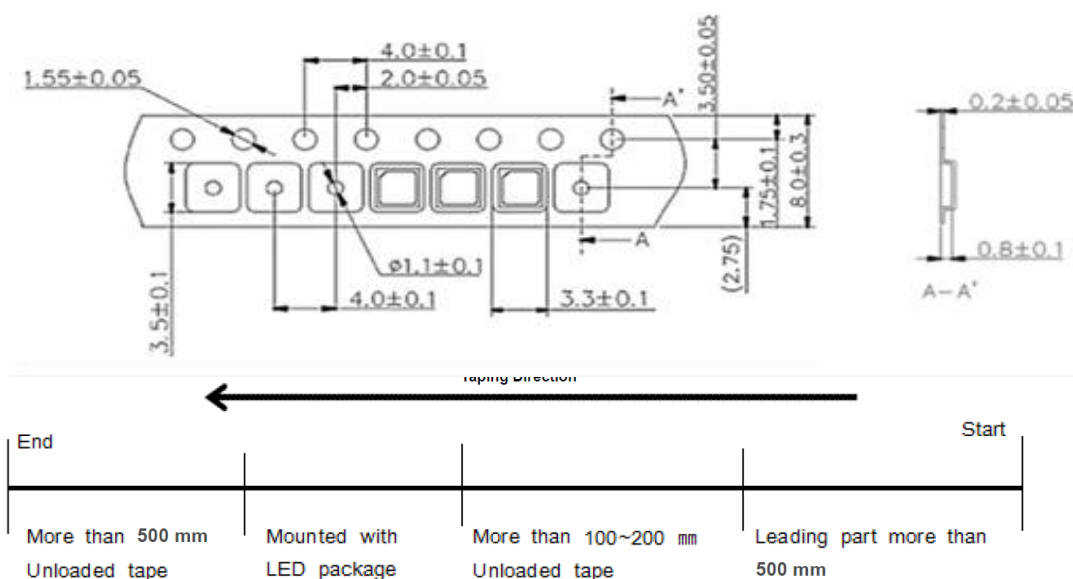
(2) Manual Soldering Conditions

Not more than 5 seconds @ max. 300 °C, under soldering iron.

6. Tape & Reel

(1) Taping Dimension

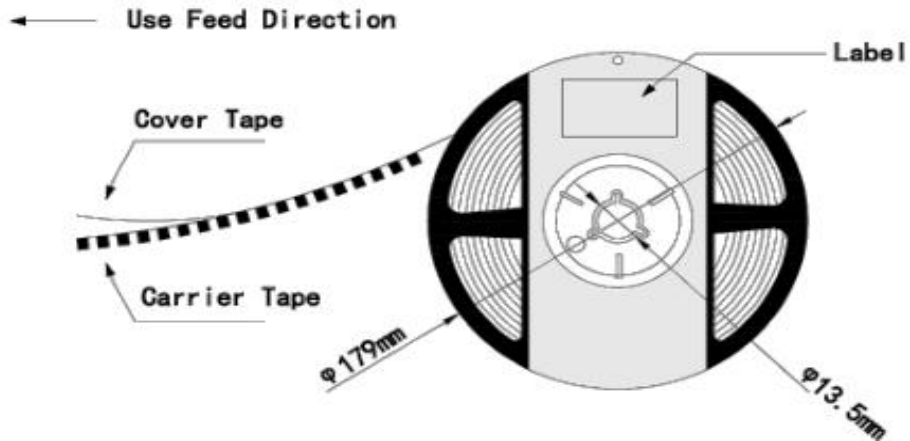
(unit : mm)



6. Tape & Reel

(2) Reel Dimension (Max 4,000 pcs)

(unit : mm)

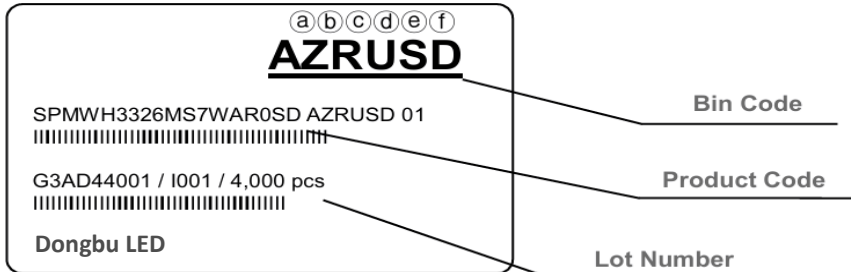


* Note :

- 1) Quantity: The quantity/reel is 4,000 pcs
- 2) Cumulative Tolerance: Cumulative tolerance / 10 pitches is ± 0.2 mm
- 3) Adhesion Strength of Cover Tape: Adhesion strength is 0.1-0.7 N when the cover tape is turned off from the carrier tape at 10° angle to the carrier tape
- 4) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag

7. Label Structure

(1) Label Structure



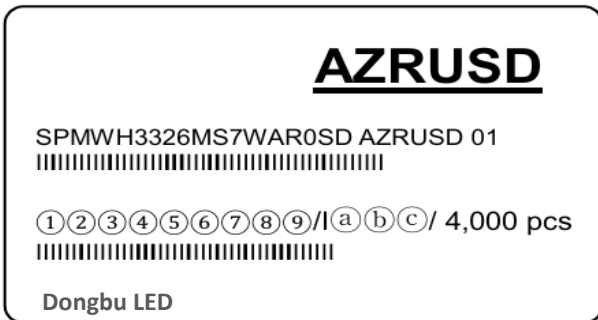
* Note : Denoted bin code and product code above is only an example (see description on page 3)

Bin Code

- ⒶⒷ: Forward Voltage bin (refer to page 4)
- ⒸⒹ: Chromaticity bin (refer to page 9)
- ⒺⒻ: Luminous Flux bin (refer to page 4, 5)

(2) Lot Number

The lot number is composed of the following characters:



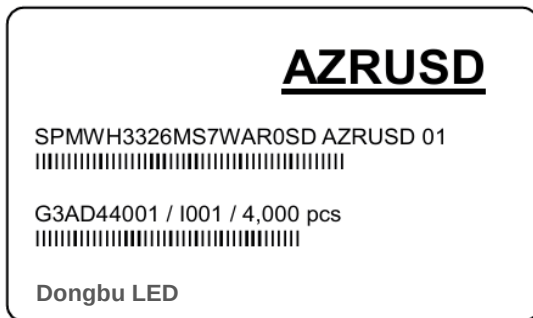
①②③④⑤⑥⑦⑧⑨ / I ⒶⒷⒸ / 4,000 pcs

- ①② : Production site (GL: Tianjin, China , G4: Guangzhou, China, E EH : HanoiHanoi, Vietnam)
- ③ : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)
- ④ : Year (C: 2018, D: 2019, E: 2020, F: 2021, G: 2022...)
- ⑤ : Month (1~9, A, B, C)
- ⑥ : Day (1~9, A, B~V)
- ⑦⑧⑨ : Serial number (001 ~ 999)
- ⒶⒷⒸ : Reel number (001 ~ 999)

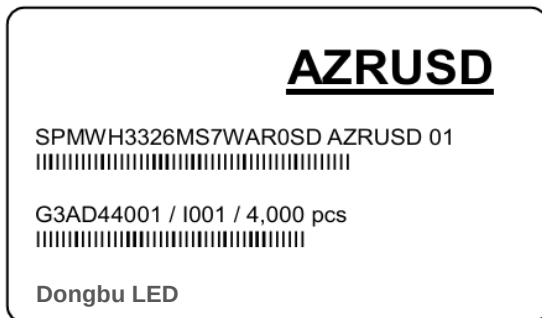
8. Packing Structure

(1) Packing Process (The quantity of PKG on the Reel to be Max 4,000 pcs)

Reel



Aluminum Vinyl Packing Bag

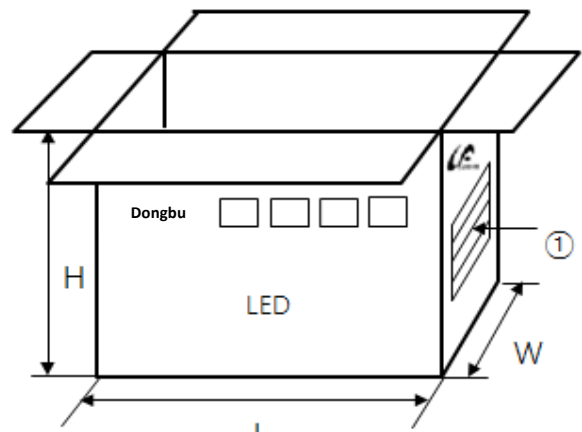
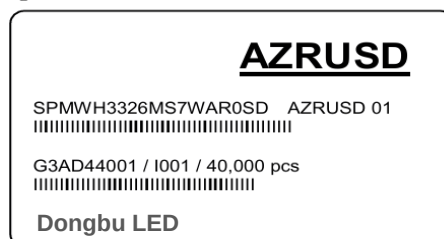


Outer Box

Material: Paper (SW3B(B))

Type	Size (mm)			Note
	L	W	H	
7 inch L	245 ± 5	220 ± 5	182 ± 5	Up to 10 reels
7 inch S	245 ± 5	220 ± 5	86 ± 5	Up to 5 reels

① Side Label

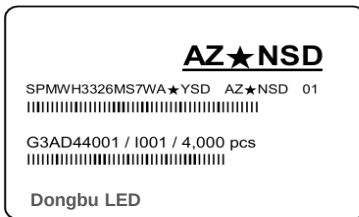


8. Packing Structure

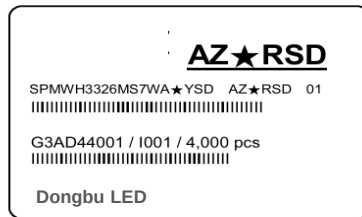
(3) Packing Process for kitting (The quantity of PKG on the Reel to be Max 4,000 pcs)

Reel

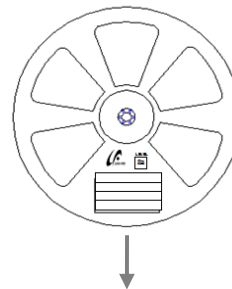
Kitting 'A'



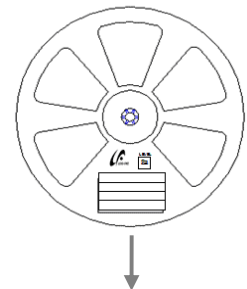
Kitting 'B'



Kitting 'A'

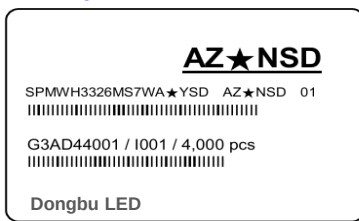


Kitting 'B'

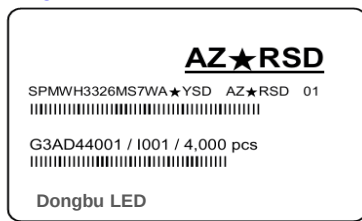


Aluminum Vinyl Packing Bag

Kitting 'A'

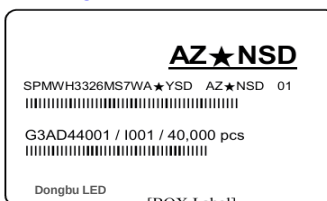


Kitting 'B'

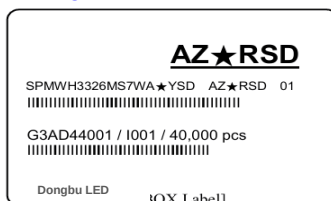


Outer Box

Kitting 'A'



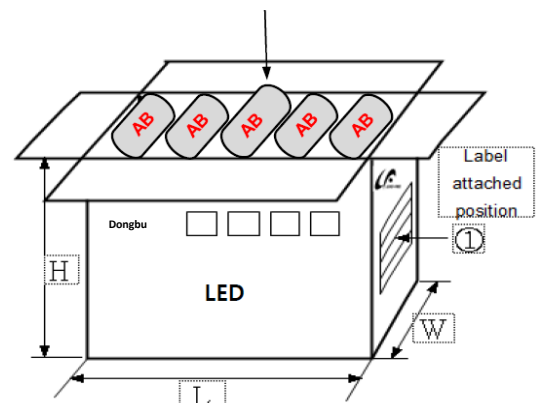
Kitting 'B'



* Note : "★" can be Nominal CCT code.

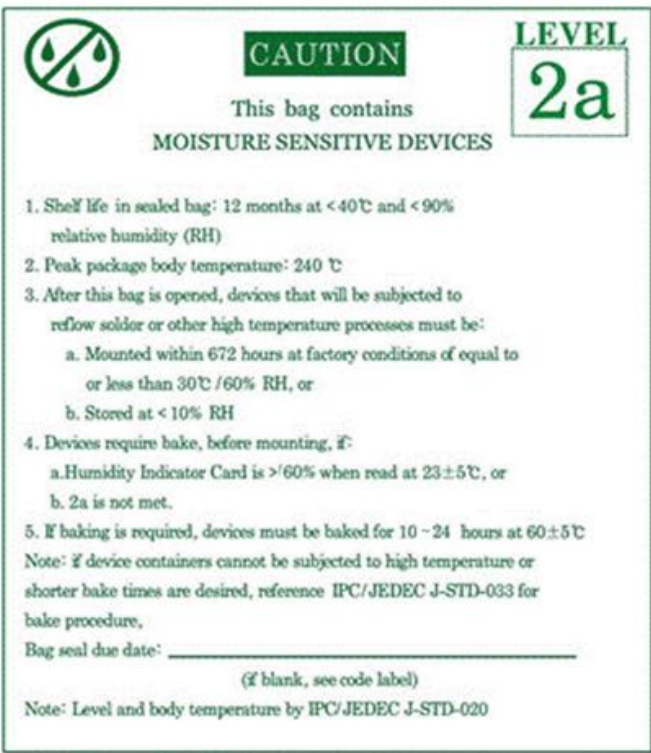
Material : Paper (SW3B(B))

Type	Size (mm)			Note
	L	W	H	
7 inch L	245 ± 5	220 ± 5	182 ± 5	Up to 10 reels



8. Packing Structure

(5) Aluminum Vinyl Packing Bag



CAUTION
This bag contains
MOISTURE SENSITIVE DEVICES

LEVEL 2a

1. Shelf life in sealed bag: 12 months at $<40^{\circ}\text{C}$ and $<90\%$ relative humidity (RH)
2. Peak package body temperature: 240°C
3. After this bag is opened, devices that will be subjected to reflow solder or other high temperature processes must be:
 - a. Mounted within 672 hours at factory conditions of equal to or less than 30°C / 60% RH, or
 - b. Stored at $<10\%$ RH
4. Devices require bake, before mounting, if:
 - a. Humidity Indicator Card is $>60\%$ when read at $23\pm5^{\circ}\text{C}$, or
 - b. 2a is not met.
5. If baking is required, devices must be baked for 10 ~ 24 hours at $60\pm5^{\circ}\text{C}$

Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure.

Bag seal due date: _____
(If blank, see code label)

Note: Level and body temperature by IPC/JEDEC J-STD-020

AZRUSD

SPMWH3326MS7WAR0SD AZRUSD 01
G3AD44001 / I001 / 4,000 pcs
Dongbu LED






주의 사항

이 알루미늄 지퍼 팩은 습기 및 정전기로부터 제품을 보호하기 위하여 제작되었습니다. 개봉 후에는 즉시 솔더 작업을 실시하는 것을 권장합니다.

습기 및 정전기로부터 제품을 보호 하기 위해서 개봉 후 사용하지 않는 자재는 본 팩에 넣어 보관 하시기 바랍니다. 사용하지 않는 자재를 본 팩에 넣을 때는 반드시 동봉된 드라이 팩과 함께 넣고 지퍼부분을 완전하게 밀봉하여 주시기 바랍니다.

Important

This Al Zipper bag is designed to protect the enclosed products from moisture and ESD. Once opened, the products should be soldered onto the printed circuit board immediately. When not in use, please do not leave the products unprotected by the Al Zipper Bag. To repack unused products, please ensure the zip-lock is completely sealed with the dry pack left inside.

(6) Silica Gel & Humidity Indicator Card inside Aluminum Vinyl Bag

(This image is for reference only. Silica gel and humidity indicator shapes may be different.)



9. Precautions in Handling & Use

- (1) For over-current protection, users are recommended to apply resistors connected in series with the LEDs to mitigate sudden change of the forward current caused by shift of forward voltage.
- (2) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When cleaning is required, IPA is recommended as the cleaning agent. Some solvent-based cleaning agent may damage the silicone resins used in the device.
- (3) When the device is in operation, the forward current should be carefully determined considering the maximum ambient temperature and corresponding junction temperature.
- (4) LEDs must be stored in a clean environment.
(shelf life of sealed bags is 12 months at temperature 0~40 °C, 0~90 % RH).
- (5) After storage bag is opened, device subjected to soldering, solder reflow, or other high temperature processes must be:
 - a. Mounted within 672 hours (28 days) at an assembly line with a condition of no more than 30 °C / 60 % RH*_{Note 1}, or
 - b. Mounted within 24 hours (1 day) at an assembly line with a condition of more than 30 °C / 70 % RH*_{Note 2}, or
 - c. Stored at <10 % RH

*Note 1, 2: IPC/JEDEC J-STD-033A, Recommended Equivalent Total Floor Life Table

Package Type and Body Thickness	Moisture Sensitivity Level	Maximum Percent Relative Humidity						Temperature
		40%	50%	60%	70%	80%	90%	
Body Thickness <2.1mm	Level2a	∞	∞	28	1	1	1	30°C
		∞	∞	∞	2	1	1	25°C
		∞	∞	∞	2	2	1	20°C

- (6) Repack unused devices with anti-moisture packing, fold to close any opening and then store in a dry place.
- (7) Devices require baking before mounting, if humidity card reading is >60 % at 23 ± 5 °C.
- (8) Devices must be baked for 10~24 hours at 60 ± 5 °C, if baking is required.
- (9) The LEDs are sensitive to the static electricity and surge current. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs. If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices. Damaged LEDs may show some unusual characteristics such as increase in leakage current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.
- (10) VOCs (Volatile Organic Compounds) can be generated from adhesives, flux, hardener or organic additives used in luminaires (fixtures). Transparent LED silicone encapsulant is permeable to those chemicals and they may lead to a discoloration of encapsulant when they exposed to heat or light. This phenomenon can cause a significant loss of light emitted (output) from the luminaires. In order to prevent these problems, we recommend users to know the physical properties of materials used in luminaires and they must be carefully selected.

9. Precautions in Handling & Use

(11) Risk of sulfurization (or tarnishing)

The LED from Dongbu uses a silver-plated lead frame and its surface color may change to black (or dark colored) when it is exposed to sulfur (S), chlorine (Cl) or other halogen compound. Sulfurization of lead frame may cause intensity degradation, change of chromaticity coordinates and, in extreme cases, open circuit. It requires caution. Due to possible sulfurization of lead frame, LED should not be used and stored together with oxidizing substances made of materials such as rubber, plain paper, lead solder cream, etc.